

SOT1249B

Earless flanged LDMOST ceramic package; 6 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	LDMOST
Package type industry code	LDMOST
Package style descriptive code	CSFM (ceramic single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	F (flange mount)
Issue date	3-3-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.61	-	-	20.02	mm
E	package width	9.27	-	-	9.53	mm
A	seated height	3.45	-	-	4.75	mm
e	nominal pitch	-	-	8.89	-	m
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

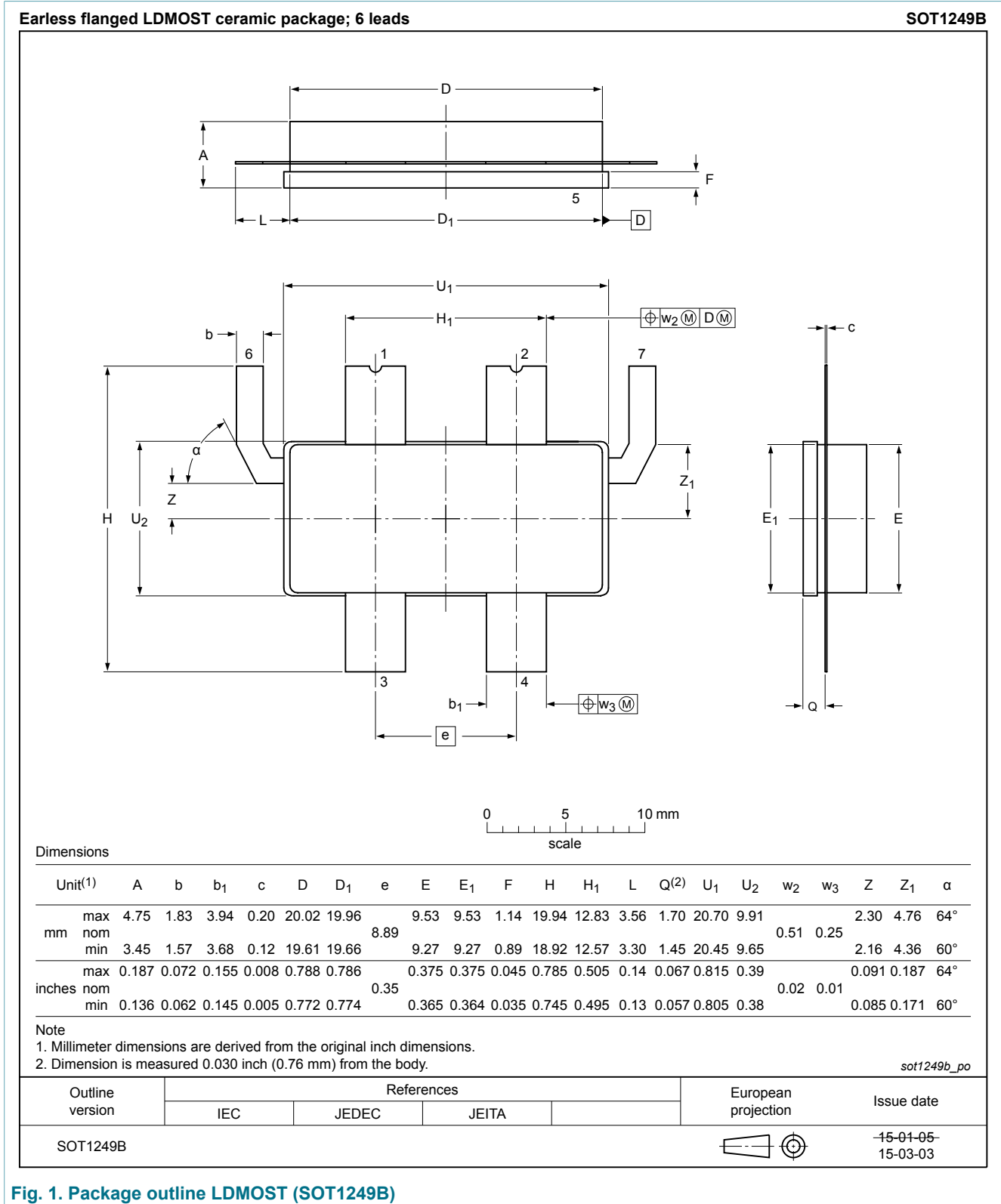


Fig. 1. Package outline LDMOST (SOT1249B)

3. Legal information

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